SPN8457
N-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPN8457 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

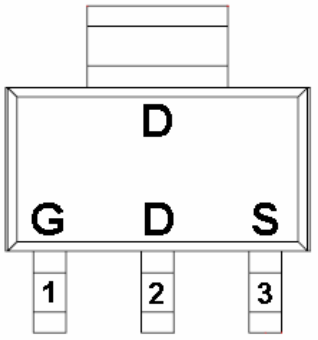
APPLICATIONS

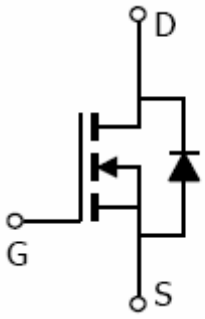
- Power Management in Note book
- DC/DC Converter
- LCD Display inverter

FEATURES

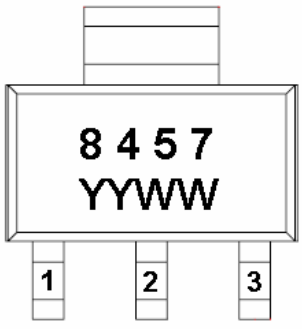
- 30V/5.5A,$R_{DS(ON)}$= 58mΩ@V_{GS}=10V
- 30V/4.0A,$R_{DS(ON)}$= 98mΩ@V_{GS}=4.5V
- Super high density cell design for extremely low $R_{DS\ (ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-223 package design

PIN CONFIGURATION(SOT-223)





PART MARKING



Y : Year Code
W : Week Code

SPN8457
N-Channel Enhancement Mode MOSFET

PIN DESCRIPTION

Pin	Symbol	Description
1	G	Gate
2	S	Source
3	D	Drain

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN8457S223RG	SOT-223	8457

※ SPN8457S223RG : Tape Reel ; Pb – Free

ABSOULTE MAXIMUM RATINGS

(T_A=25℃ Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V_{DSS}	30	V
Gate –Source Voltage		V_{GSS}	±20	V
Continuous Drain Current(T_J=150℃)	T_A=25℃	I_D	5.8	A
	T_A=70℃		4.2	
Pulsed Drain Current		I_{DM}	10	A
Continuous Source Current(Diode Conduction)		I_S	1.25	A
Power Dissipation	T_A=25℃	P_D	2.8	W
	T_A=70℃		1.2	
Operating Junction Temperature		T_J	150	℃
Storage Temperature Range		T_{STG}	-55/150	℃
Thermal Resistance-Junction to Ambient		$R_{\theta JA}$	100	℃/W

SPN8457
N-Channel Enhancement Mode MOSFET

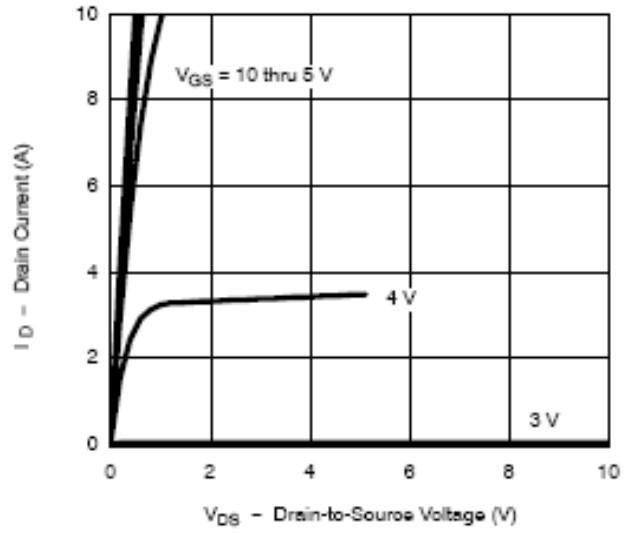
ELECTRICAL CHARACTERISTICS

(T_A=25℃ Unless otherwise noted)

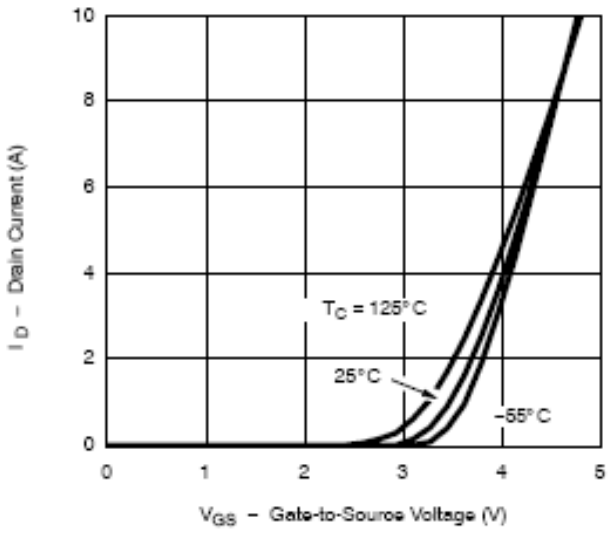
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V,I_D=250uA	30			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250uA	1.0		3.0	
Gate Leakage Current	I_{GSS}	V_{DS}=0V,V_{GS}=±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V,V_{GS}=1.0V			1	uA
		V_{DS}=30V,V_{GS}=0.0V T_J=55℃			10	
On-State Drain Current	$I_{D(on)}$	V_{DS}≧4.5V,V_{GS}=10V	6			A
		V_{DS}≧4.5V,V_{GS}=4.5V	4			
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS} = 10V,I_D=5.5A		0.050	0.058	Ω
		V_{GS} =4.5V,I_D=4.0A		0.078	0.098	
Forward Transconductance	gfs	V_{DS}=4.5V,I_D=2.5A		4.6		S
Diode Forward Voltage	V_{SD}	I_S=1.25A,V_{GS}=0V		0.82	1.2	V
Dynamic						
Total Gate Charge	Q_g	V_{DS}=15V_{GS}=10V I_D≡2.5		4.5	10	nC
Gate-Source Charge	Q_{gs}			0.8		
Gate-Drain Charge	Q_{gd}			1.0		
Input Capacitance	C_{iss}	V_{DS}=15V_{GS}=0V f=1MHz		240		pF
Output Capacitance	C_{oss}			110		
Reverse Transfer Capacitance	C_{rss}			17		
Turn-On Time	$t_{d(on)}$	V_{DD}=15R_L=15 I_D≡1.0A,V_{GEN}=10 R_G=6Ω		8	20	ns
	t_r			12	30	
Turn-Off Time	$t_{d(off)}$			17	35	
	t_f			8	20	

TYPICAL CHARACTERISTICS

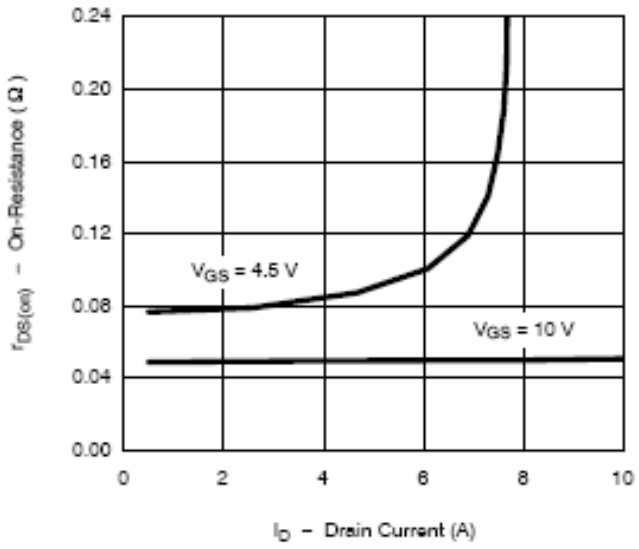
Output Characteristics



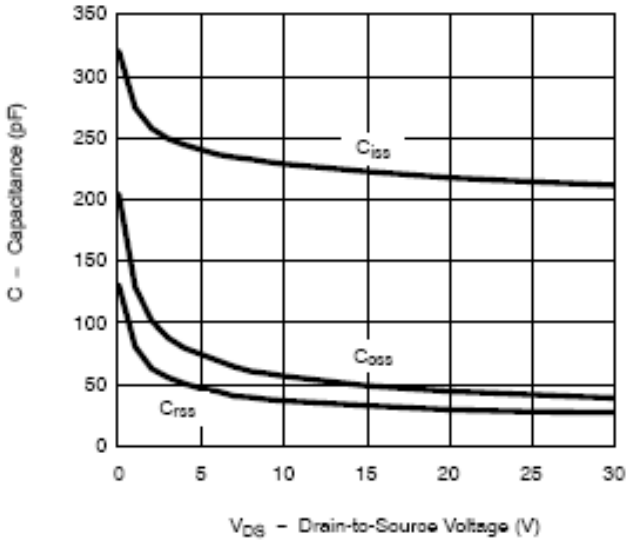
Transfer Characteristics



On-Resistance vs. Drain Current

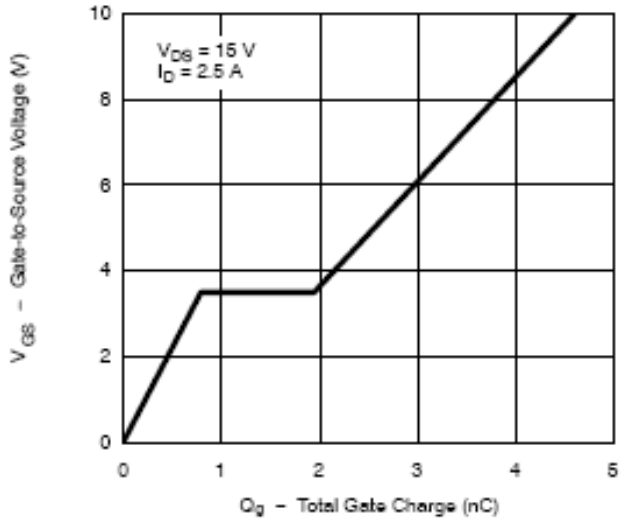


Capacitance

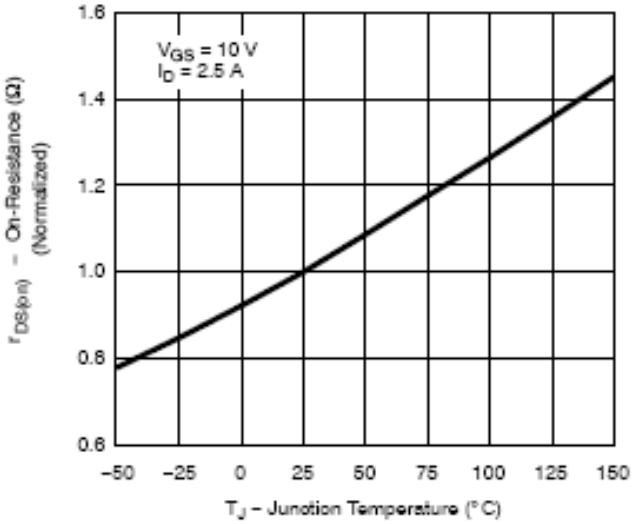


TYPICAL CHARACTERISTICS

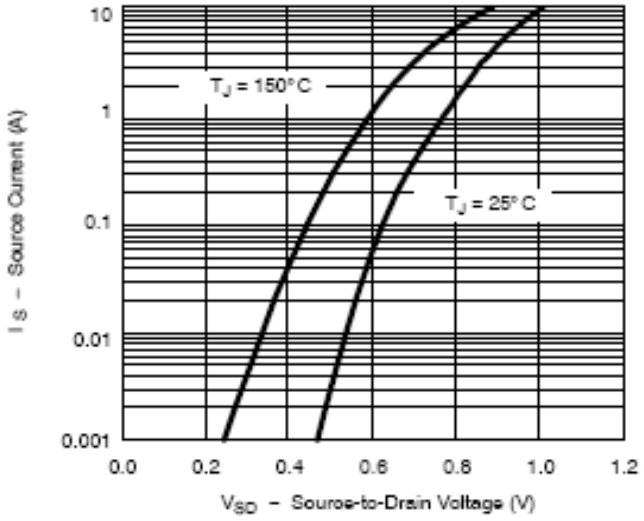
Gate Charge



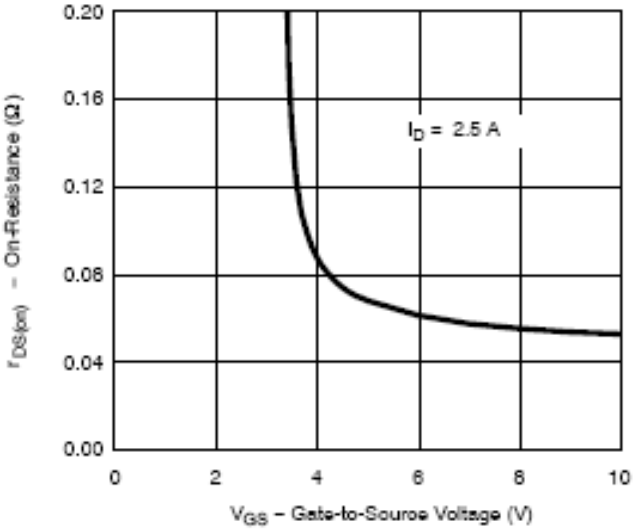
On-Resistance vs. Junction Temperature



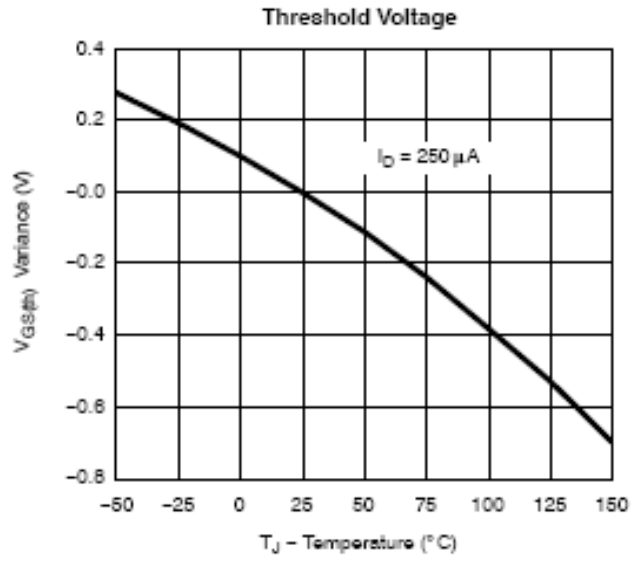
Source-Drain Diode Forward Voltage

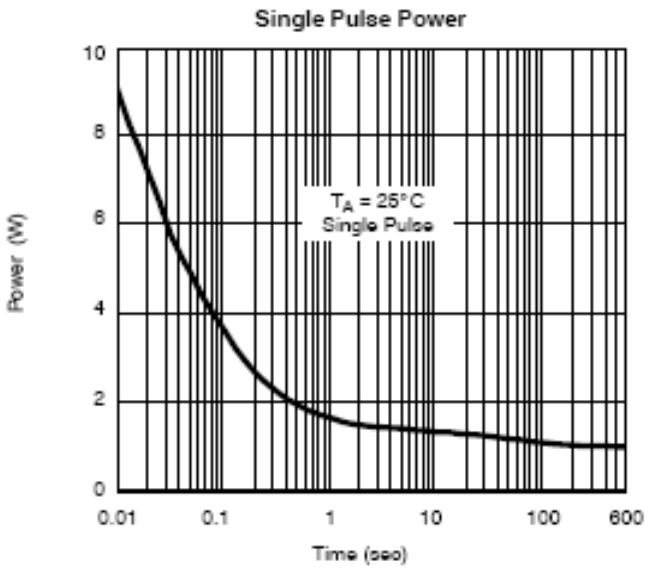


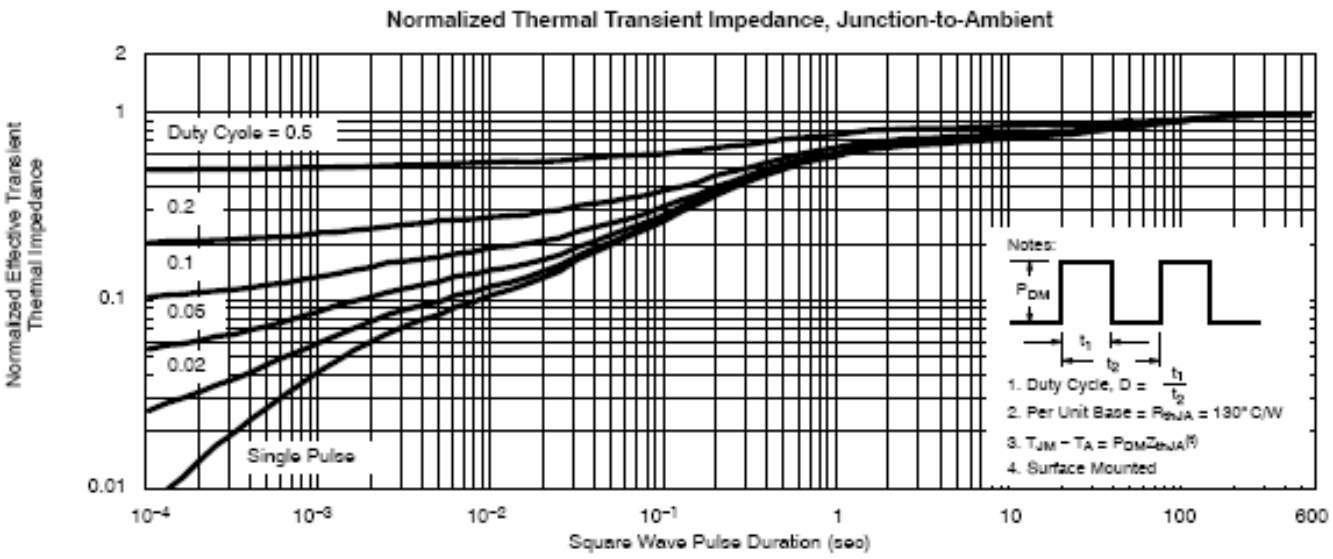
On-Resistance vs. Gate-to-Source Voltage



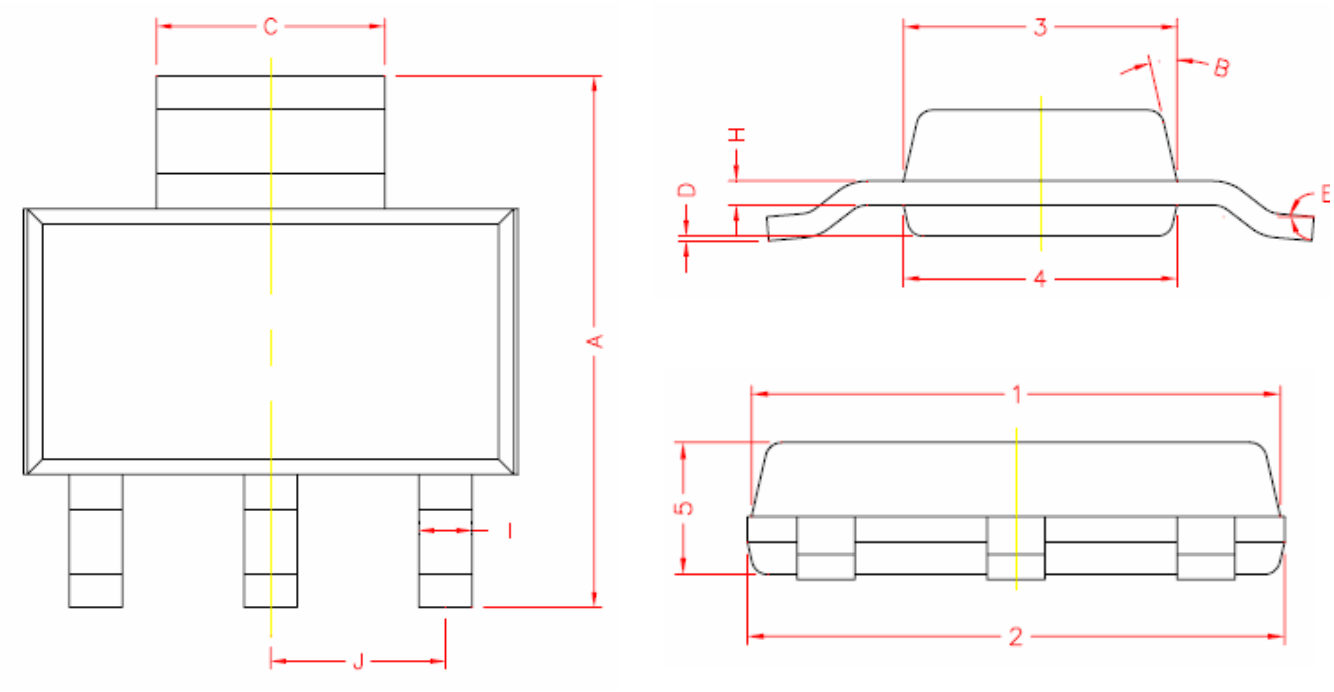
TYPICAL CHARACTERISTICS







SOT-233 PACKAGE OUTLINE



REF.	DIMENSIONS	
	Millimeters	
	Min.	Max.
A	6.70	7.30
C	2.90	3.10
D	0.02	0.10
E	0°	10°
I	0.60	0.80
H	0.25	0.35
B	13° TYP.	
J	2.30 REF.	
1	6.30	6.70
2	6.30	6.70
3	3.30	3.70
4	3.30	3.70
5	1.40	1.80

Information provided is alleged to be exact and consistent. SYNC Power Corporation presumes no responsibility for the penalties of use of such information or for any violation of patents or other rights of third parties which may result from its use. No license is granted by allegation or otherwise under any patent or patent rights of SYNC Power Corporation. Conditions mentioned in this publication are subject to change without notice. This publication surpasses and replaces all information previously supplied. SYNC Power Corporation products are not authorized for use as critical components in life support devices or systems without express written approval of SYNC Power Corporation.

©The SYNC Power logo is a registered trademark of SYNC Power Corporation
©2004 SYNC Power Corporation – Printed in Taiwan – All Rights Reserved
SYNC Power Corporation
9F-5, No.3-2, Park Street
NanKang District (NKSP), Taipei, Taiwan, 115, R.O.C
Phone: 886-2-2655-8178
Fax: 886-2-2655-8468
©http://www.syncpower.com